



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-01-31
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Patrizia Santoro	Representative Title	AMS/IPD MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TS9222IYPT	KD6P*0922BS6	A	BO2A	2013-01-31
Amount		UoM	Unit type	ST ECOPACK Grade
34.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	NiThPdAgAu	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	3x4.4x1	8	gull wing	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
	TSSOP 8 BODY 4.4 PITCH 0.65

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6P*0922B56					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	1.336	mg	supplier	Silicon die	Silicon	7440-21-3		1.335	mg	999251	39265
Silicon Die				supplier	die metallization	Aluminium(Al)	7429-90-5		0.001	mg	749	29
Lead-frame	Copper & its alloys	14.635	mg	supplier	alloy	Copper (Cu)	7440-50-8		13.99	mg	955928	411471
Lead-frame				supplier	alloy	Nickel (Ni)	7440-02-0		0.436	mg	29792	12824
Lead-frame				supplier	alloy	Silicium (Si)	7440-21-3		0.095	mg	6491	2794
Lead-frame				supplier	alloy	Magnesium (Mg)	7439-95-4		0.022	mg	1503	647
Lead-frame				supplier	coating	Nickel (Ni)	7440-02-0		0.083	mg	5671	2441
Lead-frame				supplier	coating	Palladium (Pd)	7440-05-3		0.003	mg	205	88
Lead-frame				supplier	coating	Gold (Au)	7440-57-5		0.003	mg	205	88
Lead-frame				supplier	coating	Silver (Ag)	7440-22-4		0.003	mg	205	88
Die Attach	Other Organic Materials	0.643	mg	supplier	glue	Silver (Ag)	7440-22-4		0.585	mg	909798	17206
Die Attach				supplier	glue	acrylate	Proprietary		0.032	mg	49767	941
Die Attach				supplier	glue	Methacrylate	Proprietary		0.026	mg	40435	765
Bonding wirw	Copper & its alloys	0.029	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	853
Encapsulation	Other Organic Materials	17.357	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		15.222	mg	876995	447706
Encapsulation				supplier	Moulding Compound	Epoxy resin A	EC 413-900-7		0.694	mg	39984	20412
Encapsulation				supplier	Moulding Compound	Epoxy resin B	29690-82-2		0.694	mg	39984	20412
Encapsulation				supplier	Moulding Compound	phenol resin	Proprietary		0.521	mg	30017	15324
Encapsulation				supplier	Molding compound	carbon black	1333-86-4		0.052	mg	2996	1529
Encapsulation				supplier	Moulding Compound	additive	Proprietary		0.174	mg	10025	5118